

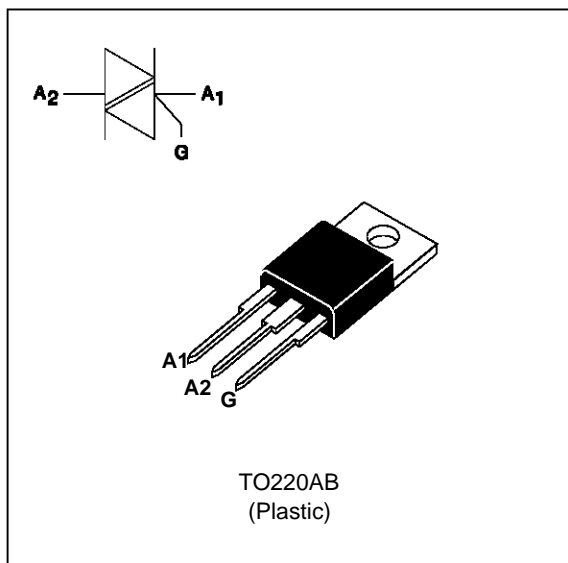
## SENSITIVE GATE TRIACS

### FEATURES

- VERY LOW  $I_{GT} = 10\text{mA}$  max
- LOW  $I_H = 15\text{mA}$  max
- BTA Family :  
 INSULATING VOLTAGE =  $2500V_{(RMS)}$   
 (UL RECOGNIZED : E81734)

### DESCRIPTION

The BTA/BTB06 T/D/S/A triac family are high performance glass passivated PNP devices. These parts are suitable for general purpose applications where gate high sensitivity is required. Application on 4Q such as phase control and static switching.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter			Value	Unit
I <sub>T(RMS)</sub>	RMS on-state current (360° conduction angle)	BTA	T <sub>c</sub> = 85°C	6	A
		BTB	T <sub>c</sub> = 90°C		
I <sub>TSM</sub>	Non repetitive surge peak on-state current ( T <sub>j</sub> initial = 25°C )		tp = 8.3 ms	63	A
			tp = 10 ms	60	
I <sup>2</sup> <sub>t</sub>	I <sup>2</sup> <sub>t</sub> value		tp = 10 ms	18	A <sup>2</sup> s
di/dt	Critical rate of rise of on-state current Gate supply : I <sub>G</sub> = 50mA   di <sub>G</sub> /dt = 0.1A/μs		Repetitive F = 50 Hz	10	A/μs
			Non Repetitive	50	
T <sub>stg</sub> T <sub>j</sub>	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 110	°C °C
T <sub>l</sub>	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			260	°C

Symbol	Parameter	BTA / BTB06-			Unit
		400 T/D/S/A	600 T/D/S/A	700 T/D/S/A	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 110^\circ\text{C}$	400	600	700	V

**THERMAL RESISTANCES**

Symbol	Parameter		Value	Unit
Rth (j-a)	Junction to ambient		60	°C/W
Rth (j-c) DC	Junction to case for DC	BTA	4.4	°C/W
		BTB	3.2	
Rth (j-c) AC	Junction to case for 360° conduction angle ( F= 50 Hz)	BTA	3.3	°C/W
		BTB	2.4	

**GATE CHARACTERISTICS** (maximum values)

$P_G$  (AV) = 1W     $P_{GM}$  = 10W (tp = 20 μs)     $I_{GM}$  = 4A (tp = 20 μs)     $V_{GM}$  = 16V (tp = 20 μs).

**ELECTRICAL CHARACTERISTICS**

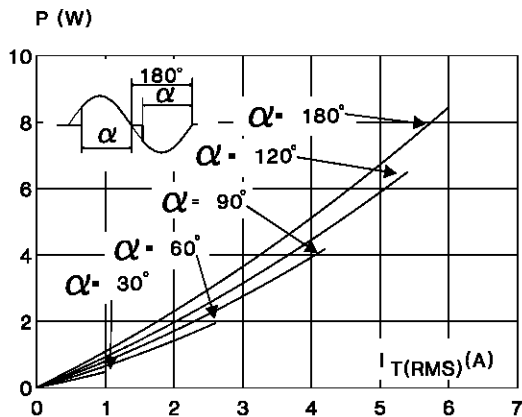
Symbol	Test Conditions		Quadrant		Suffix				Unit
					T	D	S	A	
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MAX	5	5	10	10	mA
			IV	MAX	5	10	10	25	
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III-IV	MAX	1.5				V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =110°C	I-II-III-IV	MIN	0.2				V
tgt	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 40mA dI <sub>G</sub> /dt = 0.5A/μs	T <sub>j</sub> =25°C	I-II-III-IV	TYP	2				μs
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	I-III-IV	TYP	10	10	20	20	mA
			II		20	20	40	40	
I <sub>H</sub> *	I <sub>T</sub> = 100mA gate open	T <sub>j</sub> =25°C		MAX	15	15	25	25	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 8.5A tp= 380μs	T <sub>j</sub> =25°C		MAX	1.65				V
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>DRM</sub> Rated V <sub>RRM</sub> Rated	T <sub>j</sub> =25°C		MAX	0.01				mA
		T <sub>j</sub> =110°C	MAX	0.75					
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> =110°C		TYP	10	10	-	-	V/μs
				MIN	-	-	10	10	
(dV/dt) <sub>c</sub> *	(dI/dt) <sub>c</sub> = 2.7A/ms	T <sub>j</sub> =110°C		TYP	1	1	5	5	V/μs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

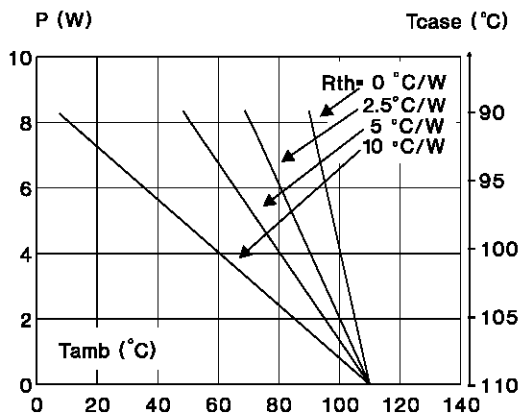
## ORDERING INFORMATION

Package	I <sub>T</sub> (RMS)	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity Specification			
	A	V	T	D	S	A
BTA (Insulated)	6	400	X	X	X	X
		600	X	X	X	X
		700	X	X	X	X
BTB (Uninsulated)		400	X	X	X	X
		600	X	X	X	X
		700	X	X	X	X

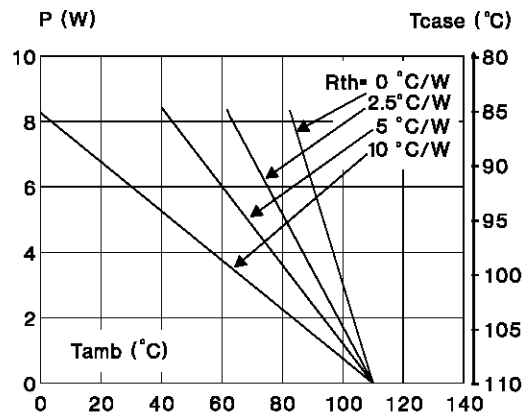
**Fig.1** : Maximum RMS power dissipation versus RMS on-state current ( $F=50\text{Hz}$ ).  
(Curves are cut off by  $(di/dt)_c$  limitation)



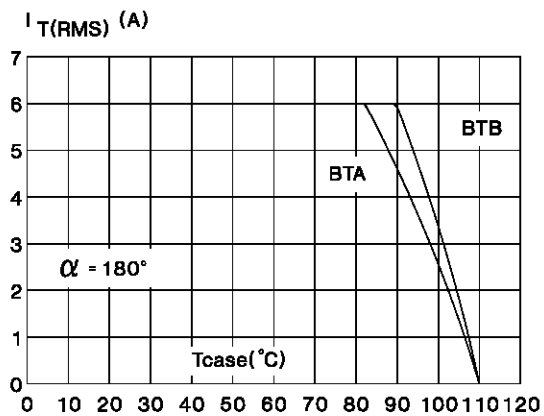
**Fig.3** : Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{\text{amb}}$  and  $T_{\text{case}}$ ) for different thermal resistances heatsink + contact (BTB).



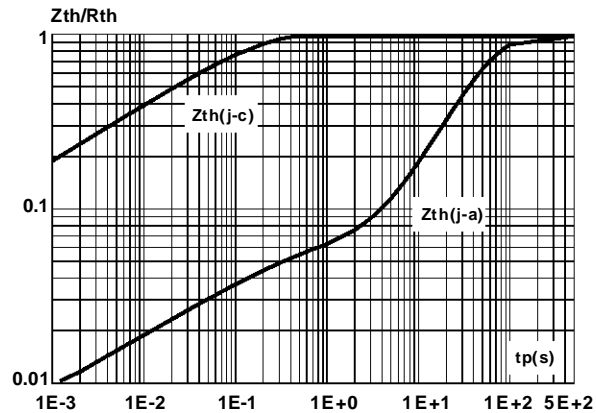
**Fig.2** : Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{\text{amb}}$  and  $T_{\text{case}}$ ) for different thermal resistances heatsink + contact (BTA).



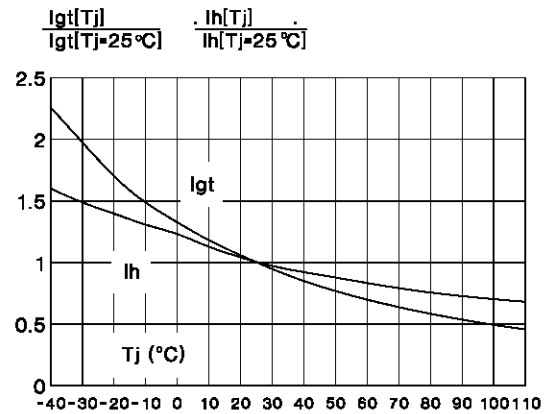
**Fig.4** : RMS on-state current versus case temperature.



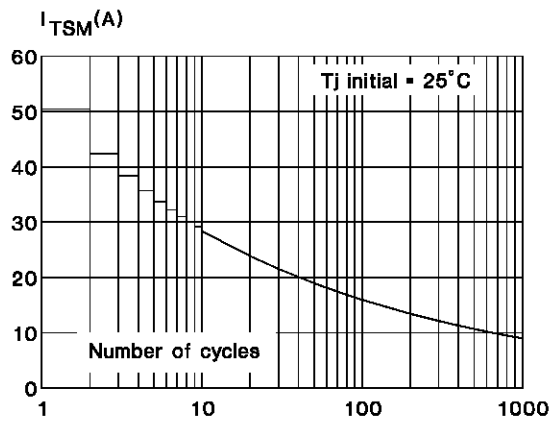
**Fig.5** : Relative variation of thermal impedance versus pulse duration.



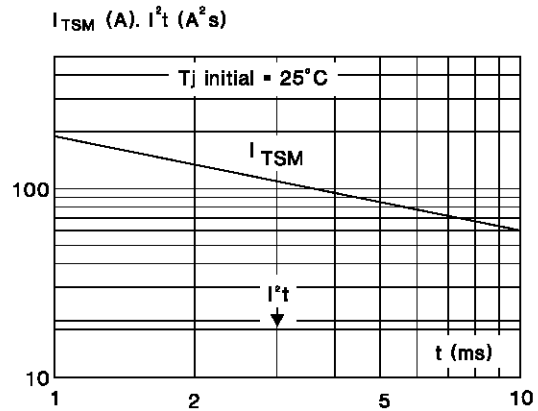
**Fig.6** : Relative variation of gate trigger current and holding current versus junction temperature.



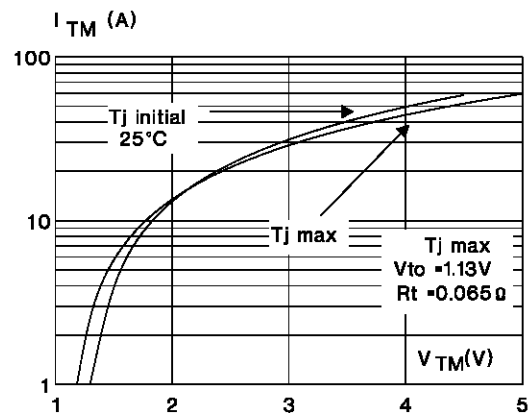
**Fig.7** : Non Repetitive surge peak on-state current versus number of cycles.



**Fig.8** : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .

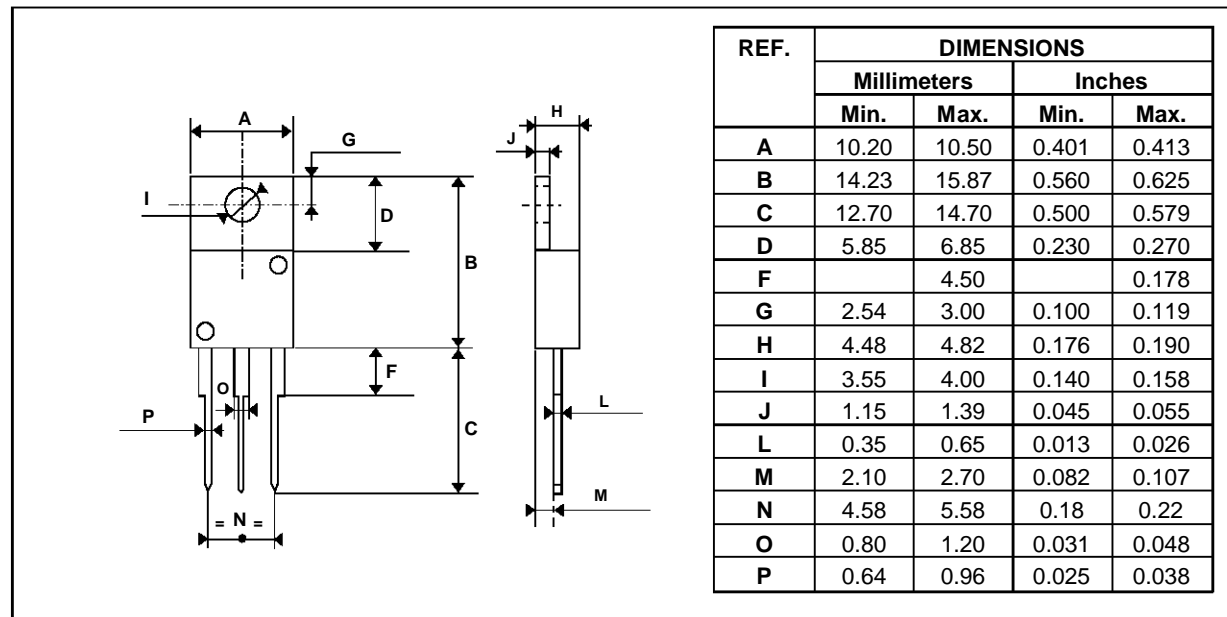


**Fig.9** : On-state characteristics (maximum values).



**PACKAGE MECHANICAL DATA**

TO220AB Plastic



Cooling method : C

Marking : type number

Weight : 2.3 g

Recommended torque value : 0.8 m.N.

Maximum torque value : 1 m.N.

Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.

SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1995 SGS-THOMSON Microelectronics - Printed in Italy - All rights reserved.

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.